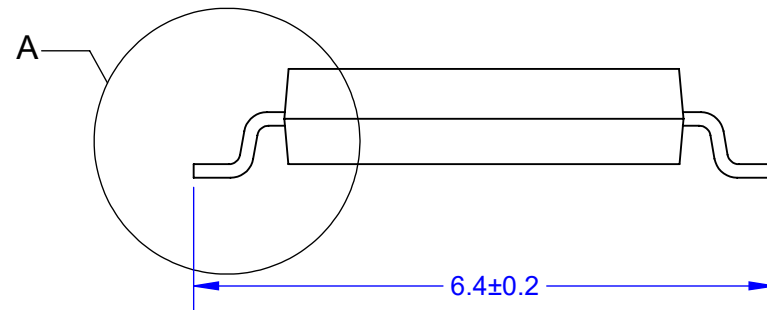
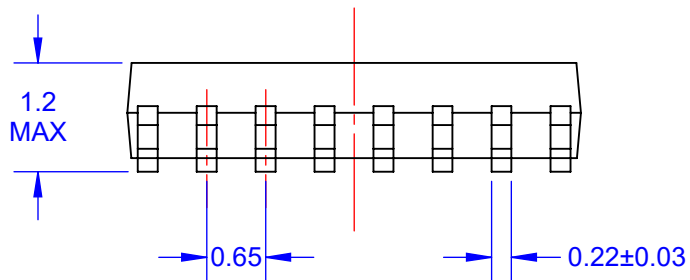
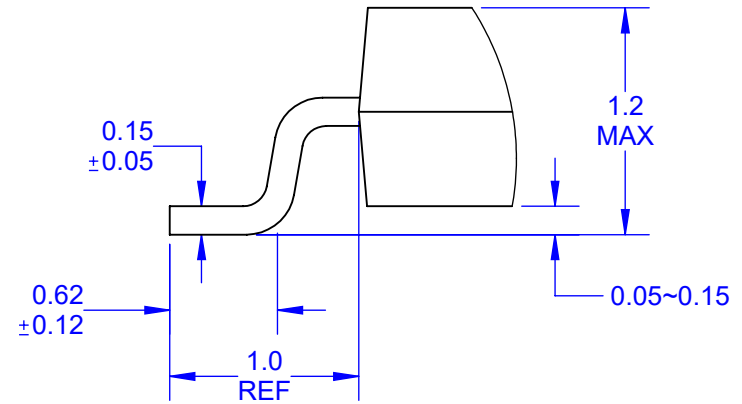


**DETAIL A  
SCALE 25 : 1**

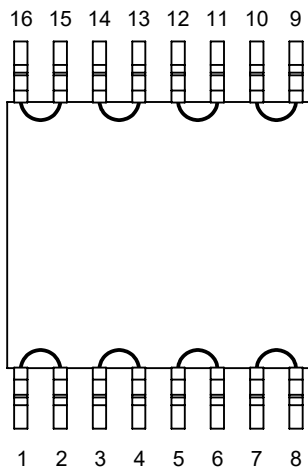


Notes: (Unless Otherwise Specified)

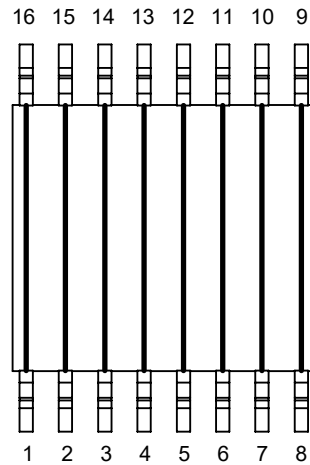
- 1) DIMENSION IN mm
- 2) SEE JUMPER DIAGRAMS (PAGE 2).
- 3) SEE PART NUMBER CONFIGURATION (PAGE 4).
- 4) RECOMMENDED PC BOARD LAYOUT PATTERN (PAGE 6).

APPROVALS		DATE	<b>TopLine®</b>			
DRAWN	T. Au	10/25/2021				
ENG	M. Hart	10/25/2021	TITLE		TSSOP16 JUMPER OUTLINE PACKAGE	
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			12:1	A	131601	A
CUST						
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 7

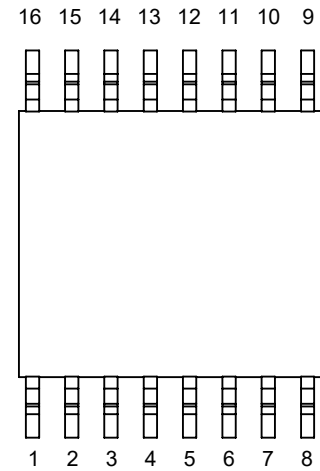
# INTERNAL WIRING CIRCUIT (JUMPER) DAISY CHAIN PART NUMBER SUFFIX TOP VIEW



**DE**  
DAISY CHAIN EVEN

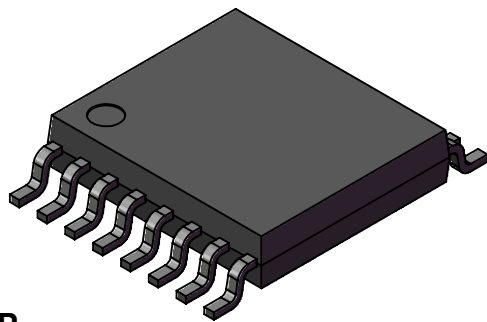


**DC1616**  
JUMPER

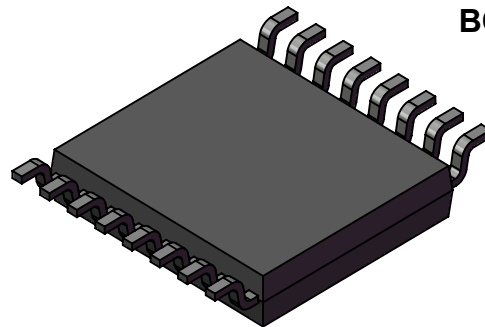


**ISO**  
ISOLATED CIRCUIT  
NO INTERNAL  
CONNECTIONS

**MODEL**



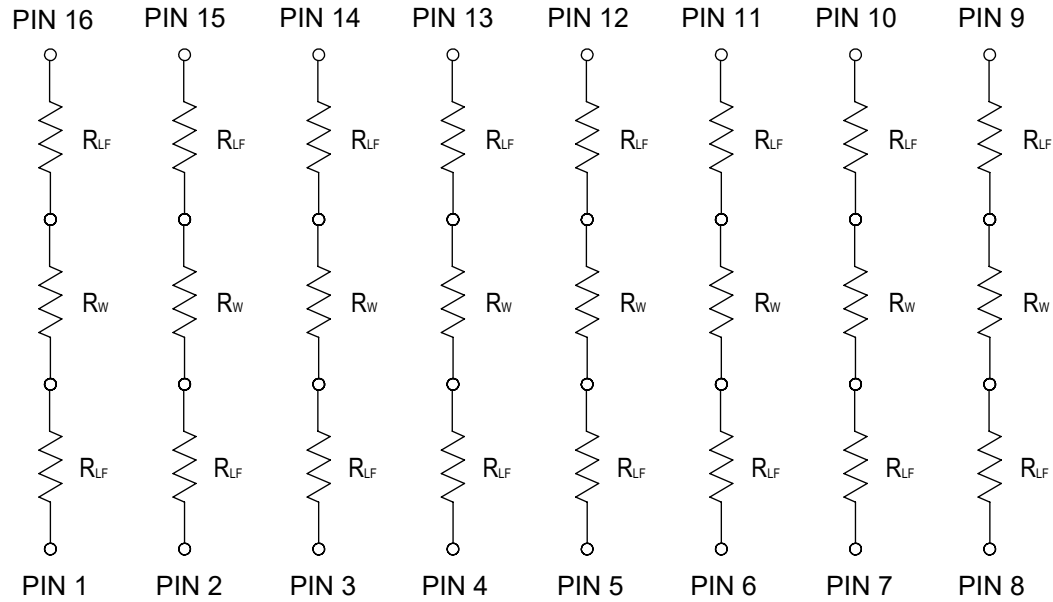
**TOP**



**BOTTOM**

<b>TopLine®</b>			
TITLE    TSSOP16 JUMPER OUTLINE PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
8:1	A	131601	A
DO NOT SCALE DRAWING			SHEET 2 OF 7

**SCHEMATIC EQUIVALENT INTERNAL CIRCUIT (DC1616)**



$R_W$  = GOLD WIRE-BOND.

$R_{LF}$  = LEAD FRAME.

**ELECTRICAL RESISTANCE MILLIOHM (DC) MAX**

CIRCUIT	PIN TO PIN
1 ~ 16	50 mΩ
2 ~ 15	50 mΩ
3 ~ 14	50 mΩ
4 ~ 13	50 mΩ
5 ~ 12	50 mΩ
6 ~ 11	50 mΩ
7 ~ 10	50 mΩ
8 ~ 9	50 mΩ

**TEMPERATURE RATING**

JUNCTION TEMP $T_J$	150°C
STORAGE TEMP $T_{stg}$	-65°C TO 150°C
OPERATING TEMP	-65°C TO 150°C
PEAK REFLOW TEMP $T_{reflow}$ 10 SECONDS	260°C

**MAXIMUM ELECTRICAL (DC) RATING PER PIN**

WORKING VOLTAGE	100 V
CURRENT RATING	100mA
POWER @ 25°C	350 mW

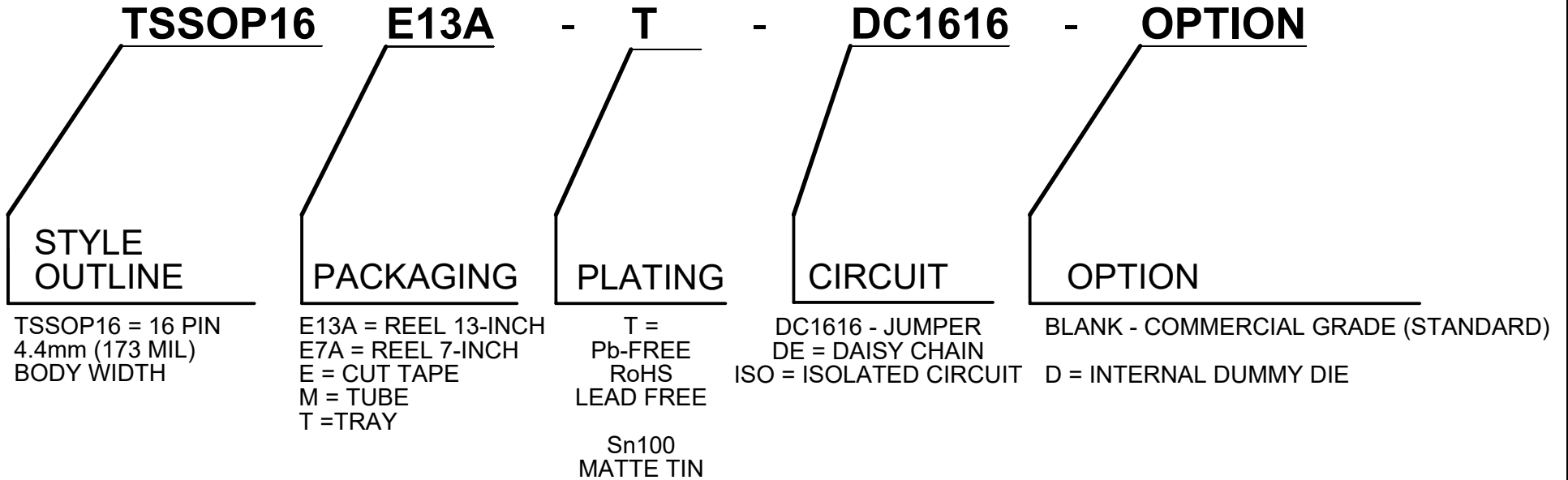
**THERMAL RESISTANCE**

JUNCTION TO AMBIENT ( $T_a=25^\circ$ ) $R_{th(j-a)}$	350K/W
---	--------

**TopLine®**

TITLE				TSSOP16 JUMPER OUTLINE PACKAGE			
SCALE	SIZE	DRAWING NO.		REV			
NONE	A	131601		A			
DO NOT SCALE DRAWING						SHEET 3 OF 7	

PART NUMBERING SYSTEM

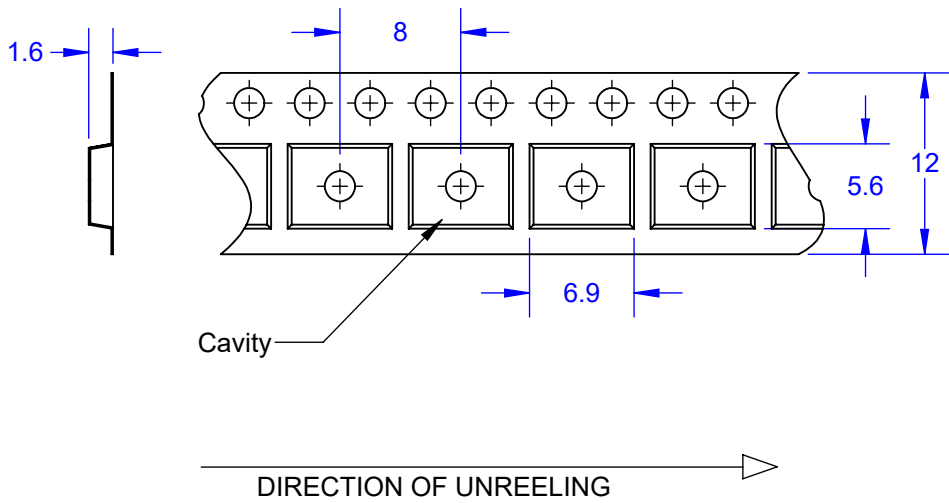


PART NUMBER	SHORTED PINS	NOTES	RoHS Pb-FREE	MSL LEVEL
TSSOP16E13A-DC1616	1~16, 2~15, 3~14, 4~13, 5~12, 6~11, 7~10, 8~9.	8-WIRES	YES	1
TSSOP16E13A-T-DE-D	1~2, 3~4, 5~6, 7~8, 9~10, 11~12, 13~14, 15~16	8-WIRES	YES	1
TSSOP16E13A-T	N/A	DUMMY	YES	1
TSSOP16E13A-T-ISO	NONE	FULLY ISOLATED	YES	1

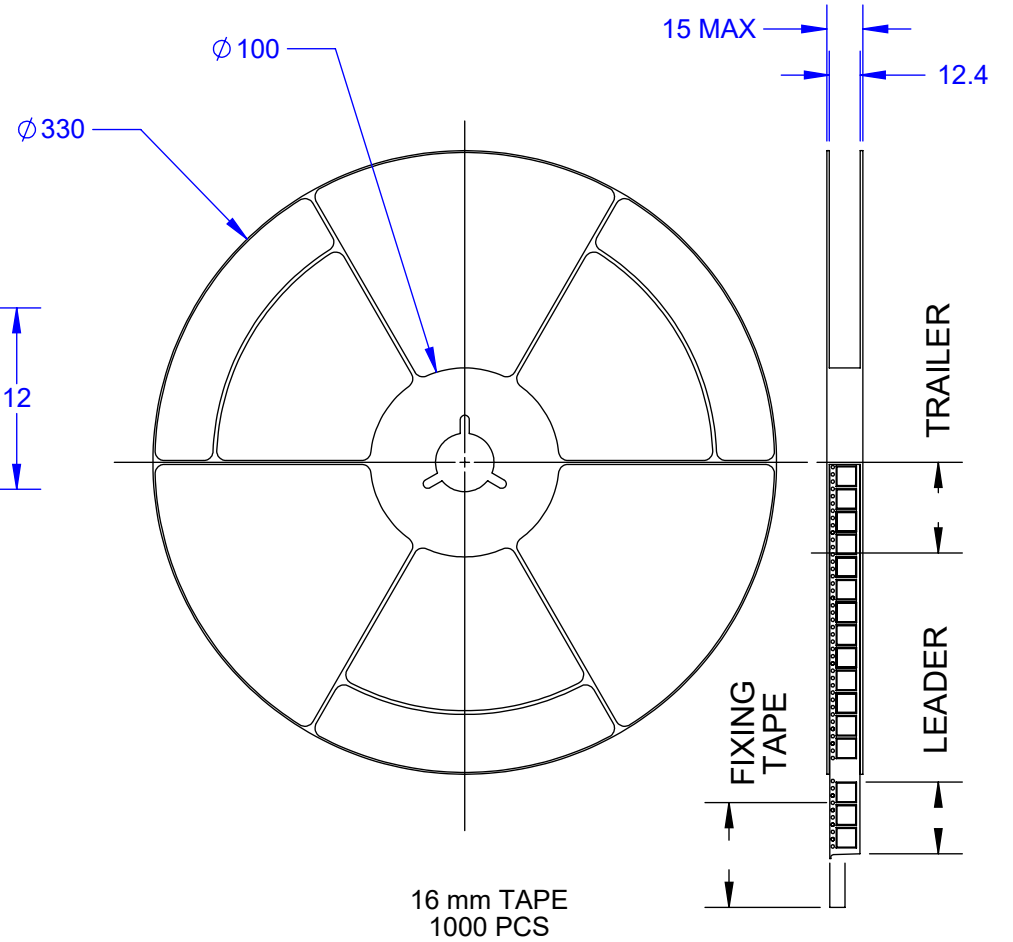
<b>TopLine®</b>			
TITLE		TSSOP16 JUMPER OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	131601	A
DO NOT SCALE DRAWING			SHEET 4 OF 7

# TAPE SPECIFICATION TSSOP16 SURFACE MOUNT DEVICE

## TAPE DIMENSIONS



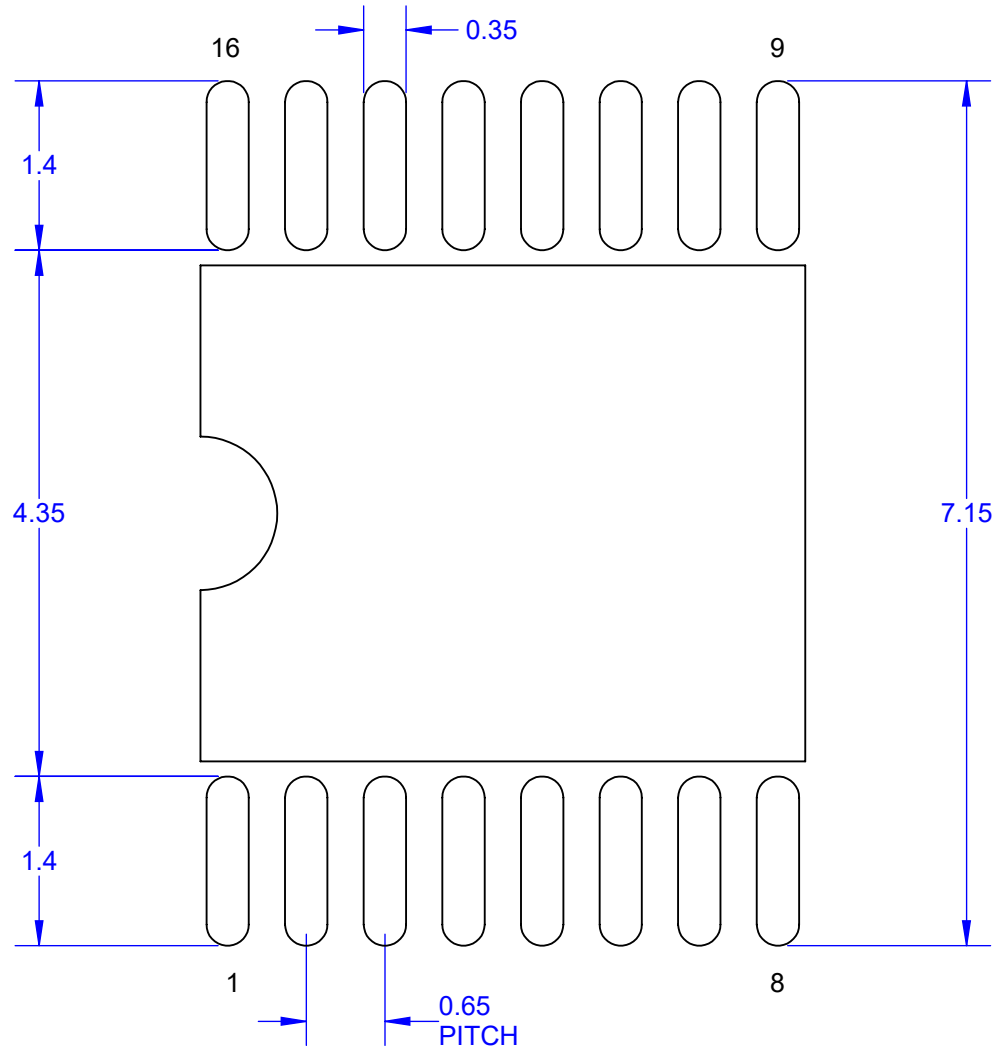
## PACKAGE REEL



ALL DIMENSIONS IN mm

<b>TopLine<sup>®</sup></b>			
TITLE		TSSOP16 JUMPER OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	131601	A
DO NOT SCALE DRAWING			SHEET 6 OF 7

# PC BOARD LAND PATTERN



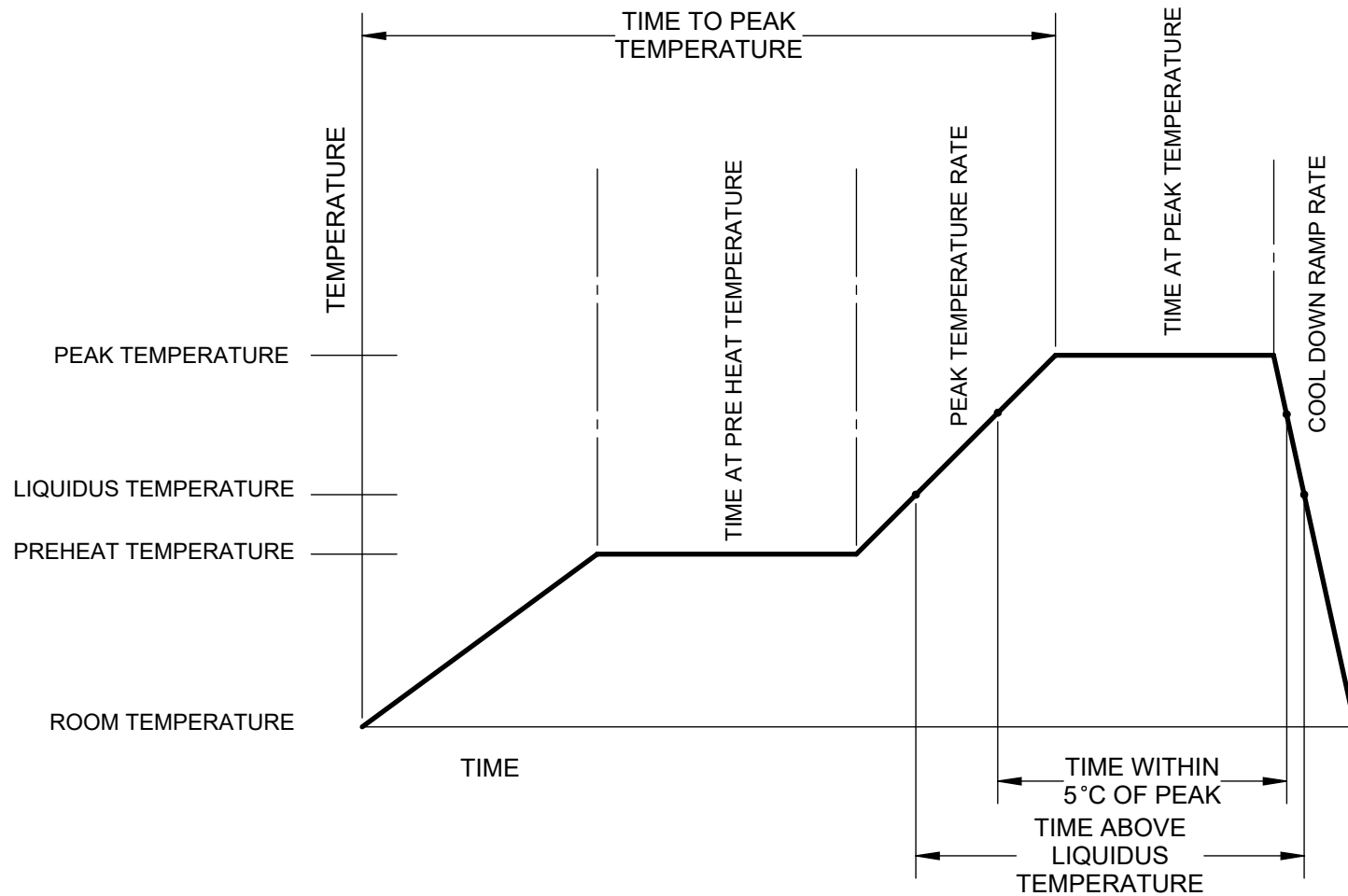
Notes: (Unless Otherwise Specified)

- 1) DIMENSIONS ARE IN INCH (mm).
- 2) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
- 3) DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

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TITLE			
TSSOP16 JUMPER OUTLINE PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
16:1	A	131601	A
DO NOT SCALE DRAWING			SHEET 7 OF 7

# LEAD FREE REFLOW PROFILE OF SMD PACKAGE



DESCRIPTION	REQUIREMENT
AVERAGE PREHEAT RAMP RATE	3 °C/SECOND MAXIMUM
PREHEAT TEMPERATURE	150 °C MAXIMUM, 200 °C MAXIMUM
PREHEAT TIME	60 TO 80 SECONDS
RAMP TO PEAK	3 °C/SECOND MAXIMUM
TIME OVER LIQUIDUS (217°C)	60 TO 150 SECONDS
PEAK TEMPERATURE	260 °C +0/-5 °C
TIME WITHIN 5°C OF PEAK	20 TO 40 SECONDS
RAMP - COOL DOWN	6 °C/SECONDS MAXIMUM
TIME 25°C TO PEAK	8 MINUTES MAXIMUM

<b>TopLine®</b>			
TITLE		TSSOP16 JUMPER OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	131601	A
DO NOT SCALE DRAWING			SHEET 7 OF 7